

Advanced Thermal Solutions, Inc.

89-27 Access Road • Norwood, MA 02062

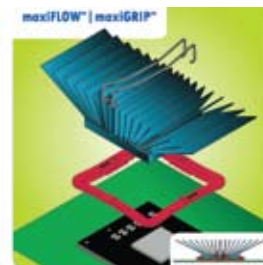
781-769-2800

www.qats.com**maxiFLOW/maxiGRIP**

ATS' maxiFLOW™ heat sinks with the maxiGRIP™ attachment system take air cooling to the limit and help reduce the cost of design and increase reliability.

The maxiFLOW™ heat sink architecture features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling. The maxiGRIP™ system features a stainless steel spring clip and plastic frame clip to provide secure attachment to the component, eliminating the need to drill holes in the PCB.

ATS' maxiFLOW™ heat sinks with maxiGRIP™ clip attachment have been successfully deployed to cool hundreds of thousands of components used by the top telecom, datacom, OEM, and contract manufacturers in the world and are available in off-the-shelf and custom sizes.

**FEATURES**

- ✦ maxiFLOW™ spread fin array heat sinks are made of lightweight, extruded aluminum which maximizes air cooling
- ✦ Reduces device junction temperatures by more than 20%, compared to heat sinks of similar volume
- ✦ The system allows for the use of high-performance phase-change materials that improve heat transfer
- ✦ maxiGRIP™ system applies steady, even pressure to the device and eliminates the need to for holes in the PCB
- ✦ Offered in 16 off-the-shelf component sizes, from 17 mm x 17 mm to 45 mm x 45 mm, and three low profile heights
- ✦ Available for overnight delivery when ordered through ATS' exclusive distributor, Digi-Key, at www.digikey.com

For more information, contact: ats@qats.comRSC# 35720 @ www.compactpci-systems.com/rsc